



YEA SHIN TECHNOLOGY CO., LTD

YS2309LCF

P-Channel Enhancement MOSFET
VDS= -20V, ID= -8.5A



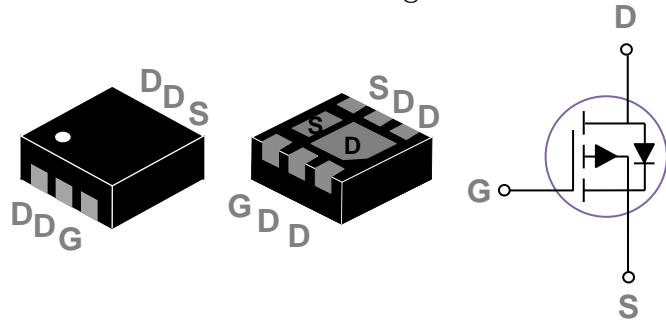
Features

- -20V,-8.5A, $R_{DS(ON)} = 28m\Omega$ @ $V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

DFN2x2-6L 2EP Pin Configuration



Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	-8.5	A
	Drain Current – Continuous ($T_c=100^\circ C$)	-5.4	A
I_{DM}	Drain Current – Pulsed ¹	-34	A
P_D	Power Dissipation ($T_c=25^\circ C$)	3.3	W
	Power Dissipation – Derate above 25°C	0.026	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	38	°C/W

DEVICE CHARACTERISTICS

YS2309LCF

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $\text{I}_D=-1\text{mA}$	---	-0.02	---	mV°C
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-20\text{V}, \text{V}_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	---	---	-1	μA
		$\text{V}_{\text{DS}}=-16\text{V}, \text{V}_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 10\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-source On-Resistance	$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-4\text{A}$	---	22	28	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-2.5\text{V}, \text{I}_D=-3\text{A}$	---	27	37	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-1.8\text{V}, \text{I}_D=-2\text{A}$	---	33	45	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=-250\mu\text{A}$	-0.3	-0.6	-1	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	2	---	mV°C
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-3\text{A}$	---	8.4	---	S

Dynamic and Switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$\text{V}_{\text{DS}}=-10\text{V}, \text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-4\text{A}$	---	16.1	25	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.8	3	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	3.8	7	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$\text{V}_{\text{DD}}=-10\text{V}, \text{V}_{\text{GS}}=-4.5\text{V}, \text{R}_G=25\Omega, \text{I}_D=-1\text{A}$	---	8.2	16	ns
T_r	Rise Time ^{2,3}		---	30	57	
$\text{T}_{\text{d(off)}}$	Turn-On Delay Time ^{2,3}		---	71.1	135	
T_f	Fall Time ^{2,3}		---	19.8	38	
C_{iss}	Input Capacitance		---	1440	2100	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=-15\text{V}, \text{V}_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	155	230	
C_{rss}	Reverse Transfer Capacitance		---	115	170	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	-8.5	A
I_{SM}	Pulsed Source Current		---	---	-17	A
V_{SD}	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=-1\text{A}, T_J=25^\circ\text{C}$	---	---	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

DEVICE CHARACTERISTICS

YS2309LCF

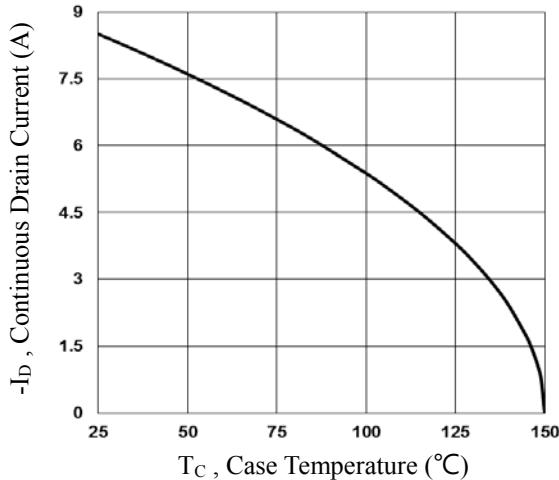


Fig.1 Continuous Drain Current vs. T_C

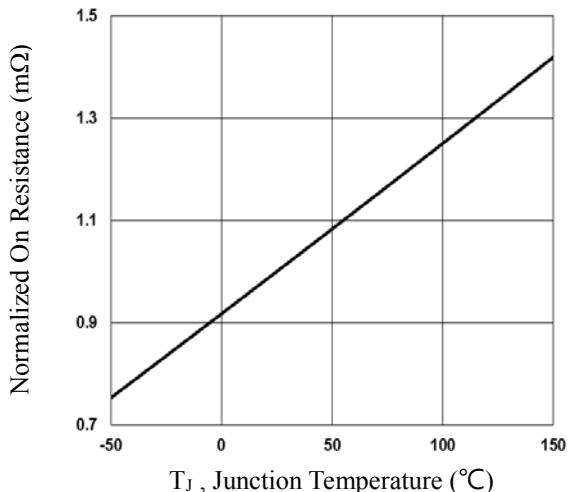


Fig.2 Normalized RD_{SON} vs. T_J

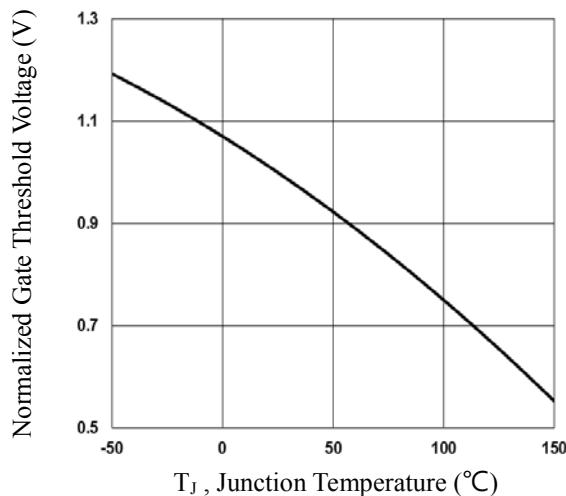


Fig.3 Normalized V_{th} vs. T_J

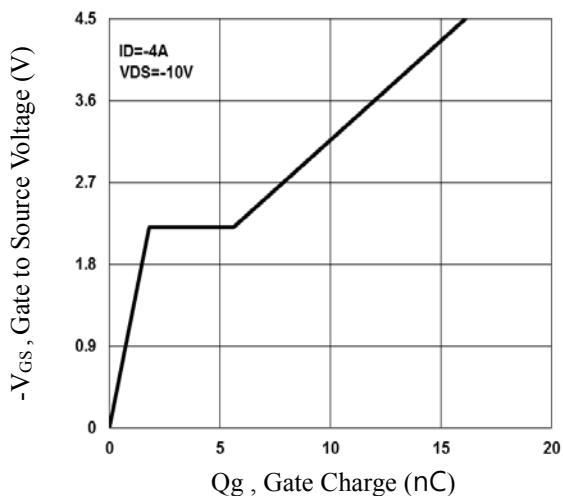


Fig.4 Gate Charge Waveform

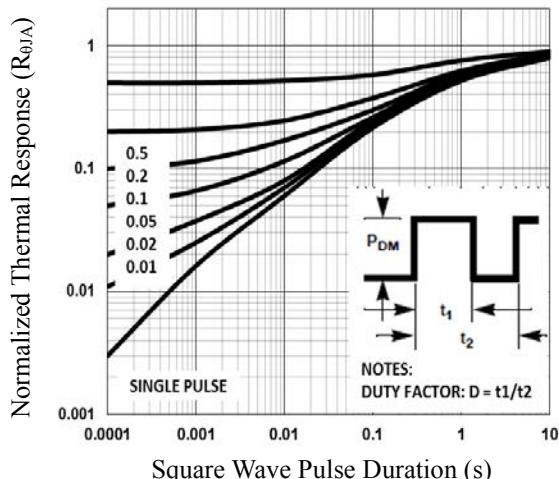


Fig.5 Normalized Transient Impedance

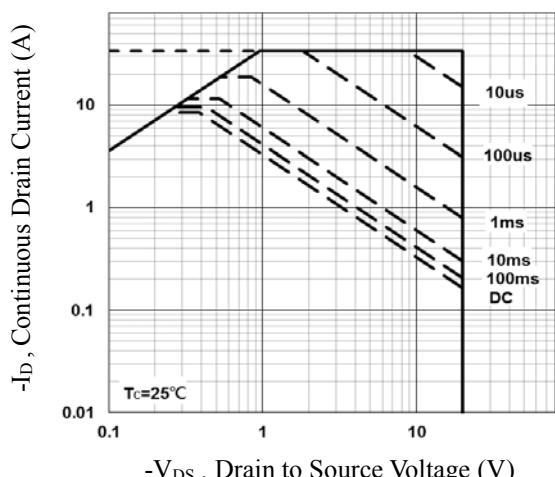


Fig.6 Maximum Safe Operation Area

DEVICE CHARACTERISTICS

YS2309LCF

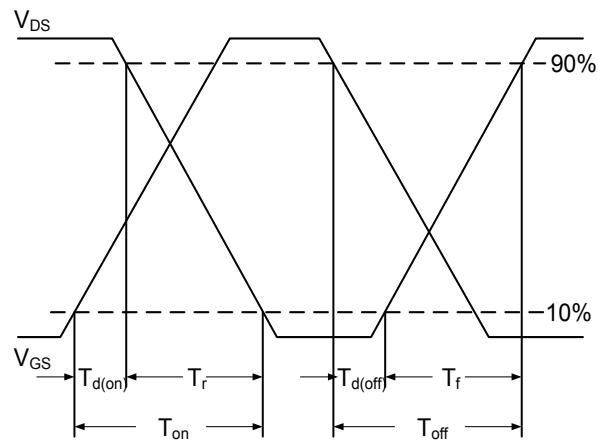


Fig.7 Switching Time Waveform

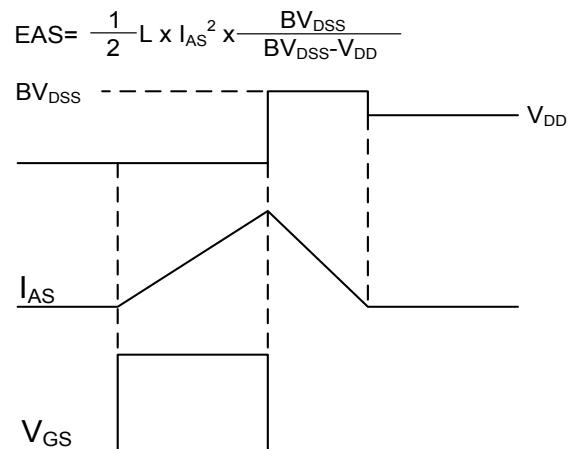
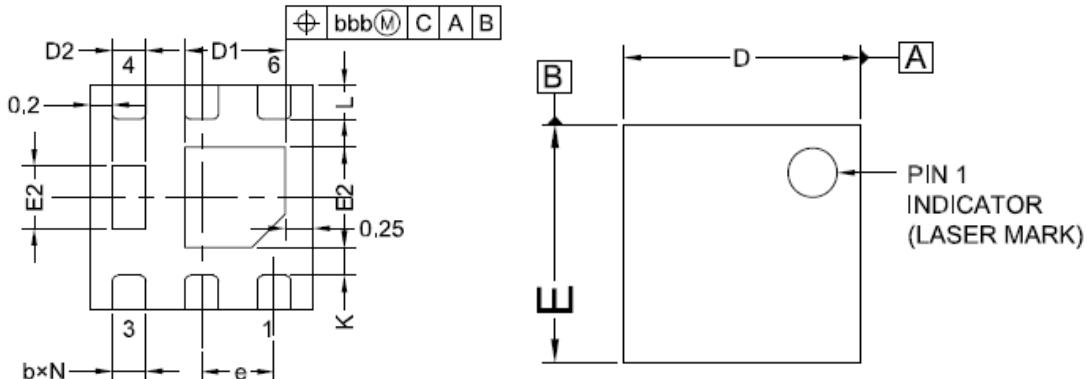


Fig.8 EAS Waveform

PACKAGE OUTLINE & DIMENSIONS

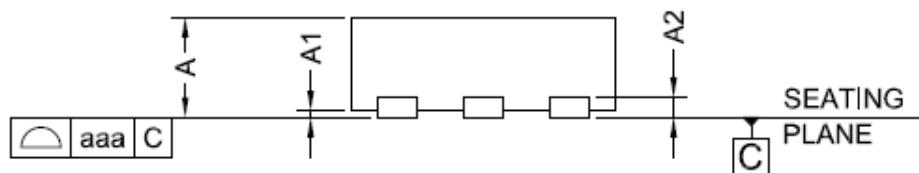
YS2309LCF

DFN2x2-6L 2EP PACKAGE INFORMATION



BOTTOM VIEW

TOP VIEW



SIDE VIEW

COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2 0.152REF.			
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.80	0.90	1.00
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.80	0.90	1.00
E2	0.46	0.56	0.66
e	0.65BSC		
L	0.25	0.30	0.35
J	0.40BSC		
K	0.20MIN		
N	6		
aaa	0.08		
bbb	0.10		